



DMB54D0UV

N-CHANNEL ENHANCEMENT MODE MOSFET PLUS PNP TRANSISTOR

Features

- N-Channel MOSFET and PNP Transistor in One Package
- Low On-Resistance
- Very Low Gate Threshold Voltage, 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- ESD Protected MOSFET Gate up to 2kV
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at https://www.diodes.com/products/automotive/automotive-products/.
- This part is qualified to JEDEC standards (as references in AEC-Q101) for High Reliability. https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Case: SOT563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Weight: 0.006 grams (approximate)

SOT563

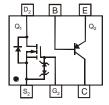




Top View



Bottom View



Top View Internal Schematic

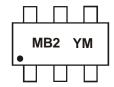
Ordering Information (Note 3)

Part Number	Case	Packaging
DMB54D0UV-7	SOT563	3,000/Tape & Reel
DMB54D0UV-13	SOT563	10,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead. Halogen and Antimony free
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
- 3. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



MB2 = Marking Code YM = Date Code Marking Y = Year (ex: V = 2008) M = Month (ex: 9 = September)

Date Code Key

Year	2008	2009	20	10	2011	2012	2013	2014	1 20	015	2016	2017
Code	V	W)	X	Υ	Z	Α	В		С	D	Е
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings – MOSFET, Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Drain-Source Voltage		V_{DSS}	50	V
Gate-Source Voltage		V _{GSS}	±12	V
Drain Current (Note 4)	Continuous	I _D	160	mA
Pulsed Drain Current (Note 4)		I _{DM}	560	mA

Maximum Ratings - PNP Transistor, Q2 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-45	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current	lc	-100	mA

Thermal Characteristics, Total Device (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 4)	P _D	250	mW
Thermal Resistance, Junction to Ambient (Note 4)	$R_{ hetaJA}$	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics - MOSFET @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	50	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 50V, V_{GS} = 0V$
Gate-Body Leakage	I _{GSS}	_	_	1.0 5.0	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0V$ $V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 5)				•	•	•
Gate Threshold Voltage	V _{GS(th)}	0.7	0.8	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance	Ь	_	3.1	4	Ω	$V_{GS} = 4V, I_D = 100mA$
Static Drain-Source On-Resistance	R _{DS (ON)}	_	4	5		$V_{GS} = 2.5V, I_D = 80mA$
Forward Transconductance	g _F s	180	_	_	mS	$V_{DS} = 10V, I_{D} = 100mA,$ f = 1.0KHz
DYNAMIC CHARACTERISTICS (Note 6)						
Input Capacitance	C _{iss}		25		pF	101/1/
Output Capacitance	Coss		5		pF	$V_{DS} = 10V, V_{GS} = 0V,$ -f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	2.1	_	pF	

otes: 4. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Short duration pulse test used to minimize self-heating effect.

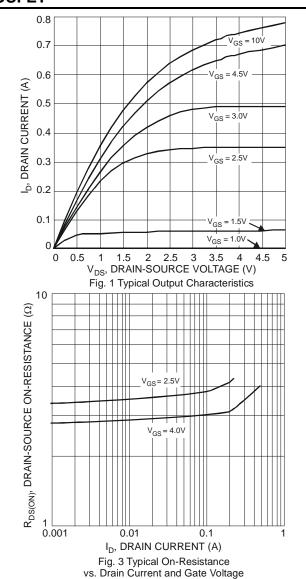
^{6.} Guaranteed by design. Not subject to product testing.

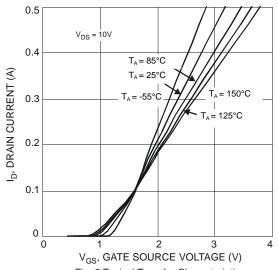


Electrical Characteristics - PNP Transistor (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage (Note 5)	V _{(BR)CBO}	-50	_	_	V	$I_C = 10\mu A, I_B = 0$
Collector-Emitter Breakdown Voltage (Note 5)	V _{(BR)CEO}	-45	_	_	V	$I_C = 10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage (Note 5)	$V_{(BR)EBO}$	-5	_	_	V	$I_E = 1\mu A, I_C = 0$
DC Current Gain (Note 5)	h _{FE}	220	290	475	1	$V_{CE} = -5.0V$, $I_{C} = -2.0mA$
Collector-Emitter Saturation Voltage (Note 5)	V _{CE} (SAT)		_	-100 -400	mV	$I_C = -10$ mA, $I_B = -0.5$ mA $I_C = -100$ mA, $I_B = -5.0$ mA
Base-Emitter Saturation Voltage (Note 5)	V _{BE(SAT)}		-700 -900		mV	$I_C = -10\text{mA}, I_B = -0.5\text{mA}$ $I_C = -100\text{mA}, I_B = -5.0\text{mA}$
Base-Emitter Voltage (Note 5)	V _{BE(ON)}	-600 —		-750 -820	mV	$V_{CE} = -5.0V, I_{C} = -2.0mA$ $V_{CE} = -5.0V, I_{C} = -10mA$
Collector-Cutoff Current (Note 5)	I _{CBO}		_	-15 -4.0	nΑ μΑ	V _{CB} = -30V V _{CB} = -30V, T _A = 150°C
Collector-Emitter Cut-Off Current (Note 5)	I _{CES}	_	_	-100	nA	V _{CE} = -45V
Gain Bandwidth Product	f⊤	100	_	_	MHz	$V_{CE} = -5.0V$, $I_{C} = -10mA$, $f = 100MHz$
Output Capacitance	C _{OB}	_	_	4.5	pF	V _{CB} = -10V, f = 1.0MHz
Noise Figure	NF		_	10	dB	$I_C = -0.2$ mA, $V_{CE} = -5.0$ Vdc, $R_S = 2.0$ K Ω , $f = 1.0$ KHz, BW = 200Hz

MOSFET





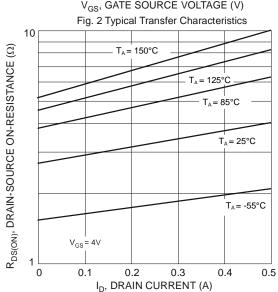
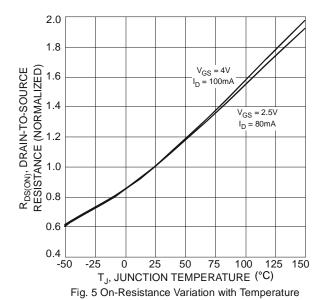
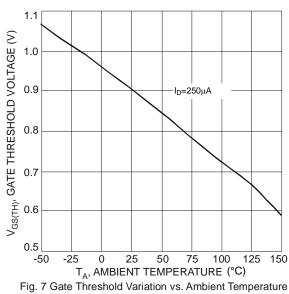
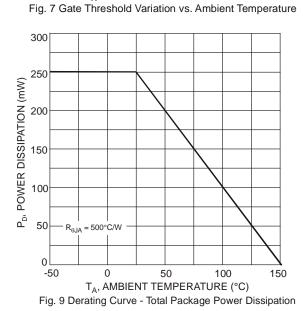


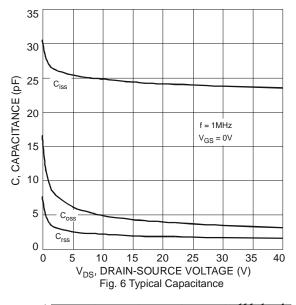
Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

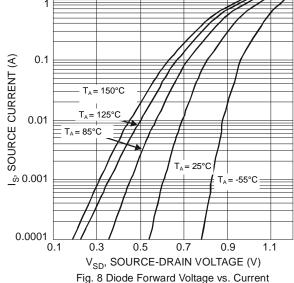














PNP Transistor

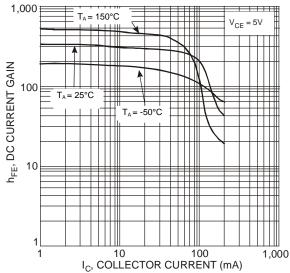
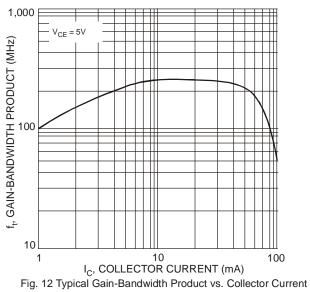


Fig. 10 Typical DC Current Gain vs. Collector Current



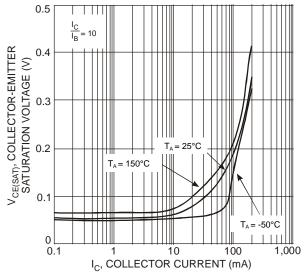
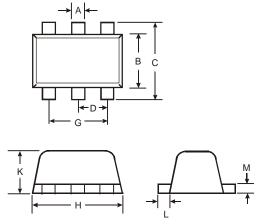


Fig. 11 Collector-Emitter Saturation Voltage vs. Collector Current



Package Outline Dimensions

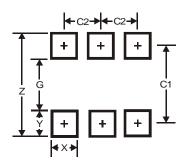
Please see http://www.diodes.com/package-outlines.html for the latest version.



	SOT563						
Dim	Min	Max	Тур				
Α	0.15	0.30	0.20				
В	1.10	1.25	1.20				
С	1.55	1.70	1.60				
D	-	-	0.50				
G	0.90	1.10	1.00				
Н	1.50	1.70	1.60				
K	0.55	0.60	0.60				
L	0.10	0.30	0.20				
М	0.10	0.18	0.11				
All	All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5



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